

SPI 2015

CALL FOR PAPERS

19th IEEE Workshop on
Signal and Power Integrity
May 10th – 13th, 2015
Berlin, Germany



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Information for Authors

Over the past eighteen years, the IEEE Workshop on Signal and Power Integrity has evolved into a forum of exchange on the latest research and developments on innovative schemes for signal and power integrity, and in the field of interconnect modeling, simulation and measurement at chip, board and package levels. The workshop is also meant to bring together developers and researchers from industry and academia in order to encourage cooperation.

In view of last year's success, the Committee is looking forward to the 19th Edition which will convene in Berlin, Germany. The symposium will include both oral and poster sessions. A number of prominent experts will be giving tutorials on areas of emerging interest.

Topics of Interest

- Innovative schemes for SI and PI
- Noise reduction techniques
- High-speed link design and modeling
- Power distribution networks
- Electronic packages and microsystems
- 3D technologies for IC and packages
- RF, microwave, mixed signal packaging
- Nano-interconnects and nano-structures
- Electromagnetic theory and modeling
- Transmission line theory and modeling
- Macro-modeling, reduced order models
- Simulation tools for SI and PI
- Electromagnetic Compatibility
- Design methodology/flow
- Measurements
- Jitter and noise modeling
- Chip-package co-design
- Novel CAD concepts

Important Dates:

Deadline for Submission of
a 2 or 4 Page Manuscript
Extended to Feb. 15, 2015

Notification of Acceptance:
February 28th, 2015



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